

深圳市强生光电科技有限公司

Shenzhen JNJ Optoelectronics Co., Limited

产品规格书

SPECIFICATION FOR APPROVAL

产品料号 ITEM	30103884
产品型号 PART NO.	JNJ-L-TO18F2(BS)-D1B-36511Z3-S1
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业务部 SERVICES DEPT.	工程部 ENGINEER DEPT.	制作 PREPARED	审核 CHECKED	批准 APPROVED
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客户接收 CUSTOMER ACCEPTANCE:		
客户名称 CUSTOMER:		
担当 SIGNED:	审核 CHECKED:	批准 APPROVED:

外观 Exterior:



图片仅供参考

产品构造 Product conformation:

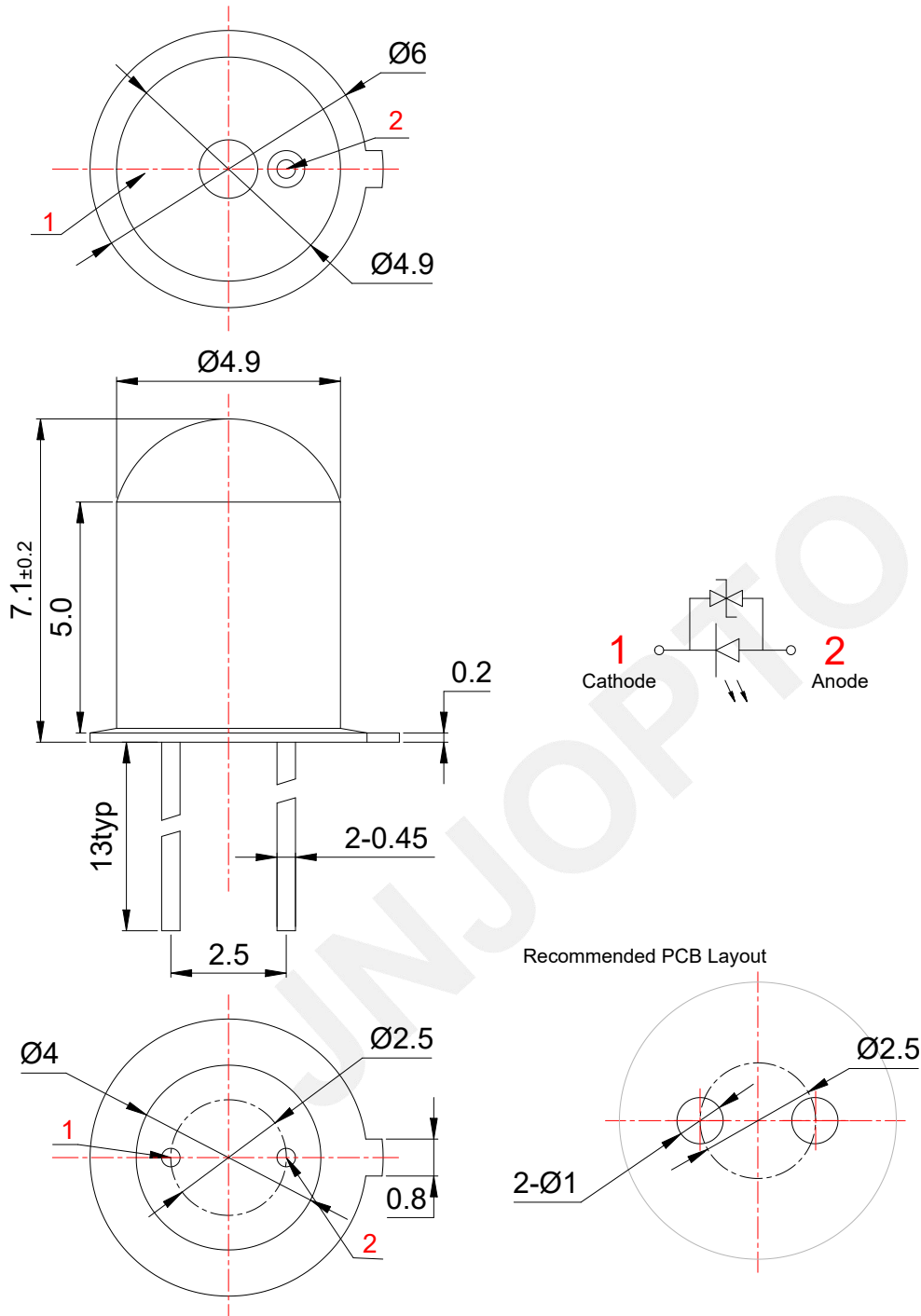
- 封装胶水: 球头管帽
Packaging: Head tube cap
- 封装支架: TO18 支架
Packaging bracket: TO18 holder
- 发光颜色: 紫光 波长 365nm+齐纳
Luminous color: Purple light has a wavelength of 365nm+zener
- 发光角度: 6 度
Luminous Angle: 6 degree
- 静电敏感材质
Electrostatic sensitive material



应用 Applications:

- 光纤通信、遥控装置 Optical fiber communication, remote control device
- 特殊照明、显示器背光 Special lighting, display and backlight
- 安防监控、夜视仪等 Security monitoring, night vision equipment, etc
- 线性发光灯具等 Linear luminescent lamps, etc

产品外形尺寸 Package outline dimensions:



备注(Note):

1. 标注尺寸单位为毫米
Dimensions are in millimeters.
2. 除特别标注外, 所有尺寸允许公差 $\pm 0.1\text{mm}$ 。
Tolerances unless mentioned are $\pm 0.1\text{mm}$.

极限参数 Absolute Maximum Rating:

参数 Parameter	符号 Symbol	额定值 Rated Value	单位 Unit	环境温度 condition Temperature
最大持续工作电流 Max Continuous Working Current	IF	≤150	mA	Ta=25°C
最大脉冲工作电流*Max Pulse Current	IFP	300	mA	Ta=25°C
反向电压 Reverse Voltage	VR	5	V	Ta=25°C
工作温度 Operating Temperature	Topr	-40°C to +100°C	°C	
存储温度 Storage Temperature	Tstg	-40°C to +100°C	°C	
回流焊温度 Reflow Soldering Temperature	Tsol	245°C for 10sec	°C	
结温 Junction Temperature	Tj	115	°C	

*Pulse condition : pulse width (tp) =100us, duty cycle=10%

光性能特点 Optical Characteristics: (Ta=25°C)

芯片 Chip	参数 Parameter	符号 Symbol	测试条件 test condition	最小 Min	典型 Typ	最大 Max	单位 Unit
U365	辐射功率 Radiant Power	Po	IF=60mA	---	45	---	mW
	辐射强度 Radiant Intensity	Iv	IF=60mA	400	550	---	mcd
	正向电压 Forward Voltage	VF	IF=60mA	---	3.5	4.0	V
	波长 Wavelength	λ	IF=60mA	---	365	---	nm
	半波宽 Half wave width	Δλ	IF=60mA	---	15	---	nm
	反向电流 Reverse current	IR	VR=5.0V	---	---	10	μA
Z3	Forward Voltage	VF	Rank C: IF = 10mA	5.5	---	7.8	V
	Forward Leakage current	IF	Rank C: VF = 5V	---	---	500	nA
	Reverse Voltage	VZ	Rank C: IR = 10mA	5.5	---	7.8	V
	Reverse Leakage current	IR	Rank C: VR = 5V	---	---	500	nA
视角 Viewing Angle	2θ1/2		---	6	---	Deg	
抗静电 Electrostatic Discharge Threshold	ESD	Human Body Model	---	---	2000	V	

备注(Note):

- θ1/2 是半值角，指辐射强度是光学中心线光强的 1/2 到光学中心线的角度
Theta 1/2 is the half-value Angle, which refers to the Angle of radiation intensity from the optical center line to the optical center line, which is 1/2 of the light intensity of the optical center line
- 上述辐射通量的测试允许公差是±10% ，电压测量误差±0.1v，波长测量误差±1nm
The test of the above radiation flux allows a tolerance of ± 10%, voltage measurement error of ± 0.1v, and wavelength measurement error of ± 1nm
- 使用时请用恒流驱动，恒压驱动时电流会偏差较大。**
Please use constant current drive, and the current deviation of constant voltage drive will be large.

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LED 芯片特性曲线 Typical Electro-Optical Characteristics Curves:

Fig.1-Relative Luminous Intensity vs. Forward Current

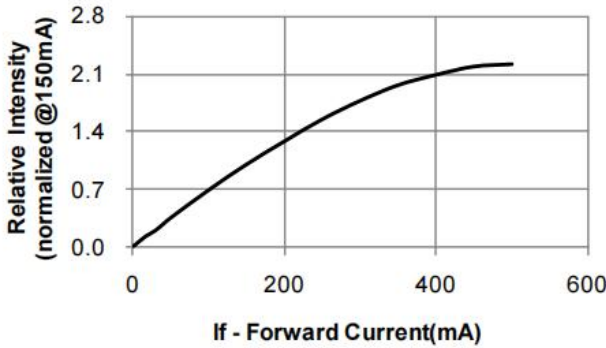


Fig.2-Forward Current vs. Forward Voltage

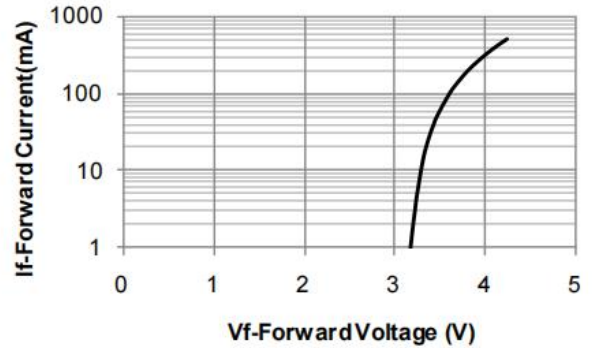
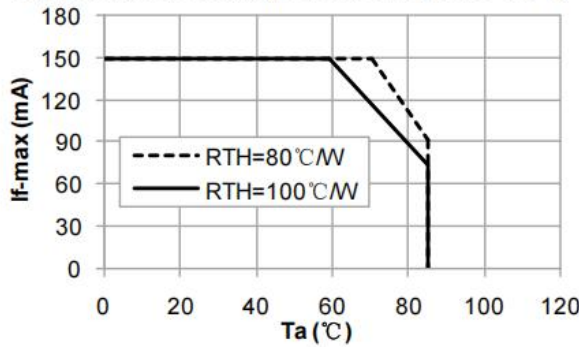
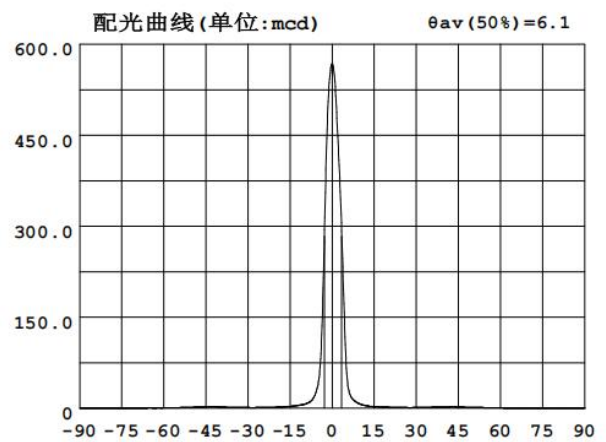
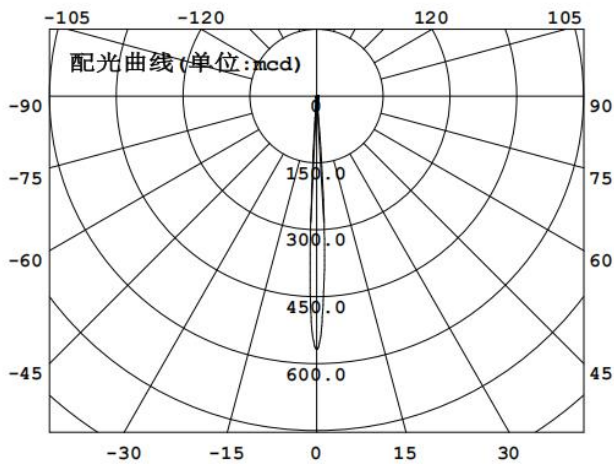


Fig.3-Maximum Driving Forward DC Current vs. Ambient Temperature (Derating based on Tj max=115°C)



LED 光强分布曲线(60mA 测试) Intensity distribution curve (60mA test):



LED 应用注意事项 Application precautions:

保存及使用 Preservation and use:

1.在打开包装前, LED 应存放在 30℃/60%RH 或以下的环境中。打开包装后, LED 应置于 20-30℃/30%RH 或以下的环境中使用。

Before opening the package, the LED should be stored at 30℃/60%RH or less. After opening the package, the LED should be placed in an environment of 20-30℃/30%RH or less.

2.molding 封装及 SMD LED 开封后要在 24H 之内使用, 为了避免环境的影响, 建议拆封后, 经过 80℃/24H 除湿, 没用完 LED 需及时做抽真空包装处理, 避免再次使用时发生失效。

To avoid the impact of the environment, it is recommended to dehumidify after unpacking at 80℃/24H. All the leds are needed to be vacuumed to avoid failure

3.若干燥剂褪色或过期使用, 需干燥烘烤: 80±5℃/24 小时。

If the desiccant faded or expired use, dry baking: 80±5℃/24 hours.

4.LED 的胶表面易沾灰尘, 需要做好相关防尘措施。

LED Glue surface easy to dust, need to do the relevant dust prevention measures.

操作注意事项 Handling Precautions

*符合 RoHS 和 REACH Compliance with RoHS and REACH

1.LED 工作环境和硫元素组成在 LED 配合使用材料中不能超过 100PPM。此信息仅供参考, 不作任何保证或背书。

LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.

2.为了防止外部物质进入 LED 内部, 导致 LED 故障, 要求溴元素的单一含量低于 900PPM, 氯元素的单一成分含量低于 900PPM, 要求应用产品外部材料中溴元素和氯元素的总含量低于 1500PPM。此信息仅供参考, 不作任何保证或背书。

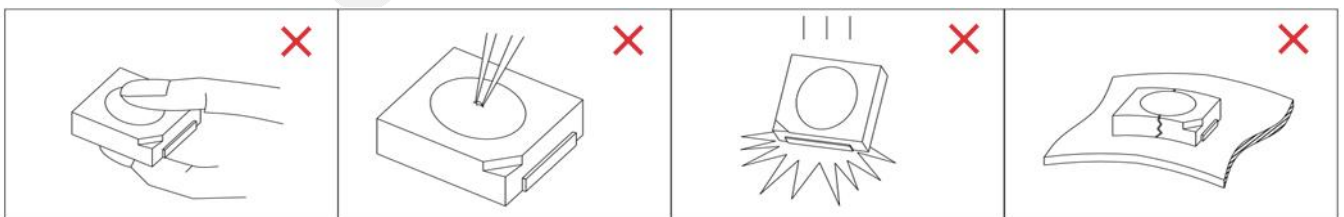
In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

3.灯具结构中使用的材料释放的挥发性有机化合物 (VOC) 会渗透到 LED 的硅胶封装中, 并在暴露于热量和光子时变色。结果可能会导致灯具的光输出大幅损失。了解用于制造灯具的材料特性有助于防止这些问题。我们建议不要使用任何已发现或怀疑对设备性能或可靠性有不利影响的化学品或材料。为了验证兼容性, 建议所有化学品和材料在其预期使用的特定应用和环境进行测试。此外, 在安装 LED 时, 避免使用会释放有机蒸气的粘合剂。

VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. We advise against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, it is recommended to test all chemicals and materials in their specific intended application and environment. Additionally, when attaching LEDs, avoid adhesives that outgas organic vapor.

4.使用镊子或合适的工具沿侧面搬运组件; 请勿直接触摸或触碰硅胶镜片表面, 否则可能会损坏内部电路。

Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or touch the silicone lens surface, it may damage the internal circuitry.



5.SMT 操作后不要堆叠。

Do not stack after SMT operation.

6.不要将 LED 存放在存在高湿度或腐蚀性化学物质的环境中, 因为它们会使 LED 的金属表面退化。

Do not store LEDs in an environment where high humidity or corrosive chemicals are present, as they will degrade the LED's metallic surfaces.

7.LED 引线框和焊盘表面镀有金、锡或其他金属。在长期暴露于露天环境下, 暴露的引脚和焊盘可能会被氧化, 导致可焊性差。因此, 打开但未使用的零件必须存放在密封容器中。建议将未使用的零件存放在原始防潮袋中。

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LED leadframe and soldering pad surfaces are plated with gold, tin, or other metals. Under long-term exposure to open air, the exposed pins and pads may become oxidized and cause poor solderability. Therefore, opened but unused parts must be stored in sealed containers. Suggest to store unused parts in the original moisture barrier bag, if possible.

8. 已安装在 PCB 上的元件的湿度控制: 如果 PCB 不进行额外的回流焊接或高温处理, 则安装的湿度敏感 SMD 元件不需要特殊处理。如果 PCB 将进行额外的回流焊接或其他高温工艺, 包括返工, 那么 SMD 组件在最终高温工艺之前的累积暴露时间必须控制在规定的暴露寿命期限内。

Moisture control for components already mounted on PCB: If the PCB will not undergo additional reflow soldering or high-temperature processes, then no special treatment is required for the mounted moisture-sensitive SMD components. If the PCB will undergo additional reflow soldering or other high-temperature processes, including rework, then the SMD component's cumulative exposure time until the final high-temperature process must be controlled to within the specified floor life time limit.

热量处理 Heat treatment

在过大电流驱动时 LED 的 T_j (节点温度) 会超过期限制值, 这导致 LED 的寿命严重缩短, 热量处理措施要有效的减小应用产品的热阻。比较通用的做法: 把 LED 封装器件安装在金属基质的 PCB 板上。1W LED 产品要求金属基板的表面散热面积至少 30cm^2 (3W 产品建议 80cm^2 以上), 且其导热系数要高于 2.0W/mK 。LED 和金属基板结合靠导热性较好的导热胶, 要求导热系数高于 1.0W/mK , 厚度小于 $100\mu\text{m}$ 。

When driven by excessive current, the T_j (node temperature) of LED will exceed the period limit value, which leads to a serious shortening of LED life. Thermal treatment measures should effectively reduce the thermal resistance of application products. Common practice: install LED packages on metal matrix PCB boards. 1W LED products require the surface heat dissipation area of the metal substrate to be at least 30cm^2 (over 80cm^2 is recommended for 3W products), and its thermal conductivity is higher than 2.0W/mK . LED and gold substrate are combined by thermal conductive adhesive with good thermal conductivity. The thermal conductivity coefficient is required to be higher than 1.0W/mK and the thickness is less than $100\mu\text{m}$.

清洁 Clean

需要清洁的话, 用干净的软碎布沾点酒精轻力擦除异物, 不可以采用诸如丙酮之类的清洁剂以免可能造成腐蚀破坏。

If you need to clean, use a clean, soft cloth dipped in alcohol to gently remove foreign matter. Do not use a cleaner such as acetone to avoid possible corrosion damage.

电性注意事项 Electrical precautions

1. LED 不允许反向驱动。

Led Reverse drive is not allowed

2. 限流措施是必要的, 否则轻微的电压变化会导致较大的电流变化, 可能造成 LED 失效。

Current limiting measures are necessary, otherwise slight voltage changes will lead to large current changes, which may lead to LED failure.

3. 在发光量满足要求的前提下, 推荐采用低于额定电流的驱动电流, 这样有利于提高产品的可靠性。

Under the premise that the luminous quantity meets the requirements, it is recommended to use the drive current lower than the rated current, which is conducive to improving the reliability of the product.

防静电措施 anti-static precautions

LED 是静电敏感器件, 在保存、使用过程中要采取防静电措施。静电和电涌会导致产品特性发生改变, 例如正向电压降低等, 情况严重甚至会损毁产品。所以对于整个工序(生产, 测试, 包装等)与 LED 直接接触的员工都要做好防止和消除静电的措施。所有相关的设备和机器都应该正确接地。接地交流电阻小于 1.0 欧姆, 工作台上需垫表面电阻 10^6 - 10^9 欧姆的桌垫。在容易产生静电的环境和设备上, 还必须安装离子风扇。作业过程中, 操作员需使用防静电手环, 防静电垫子, 防静电工作服, 工作鞋, 手套, 防静电电容等。

LED is electrostatic sensitive devices, in the process of preservation, use to take anti-static measures. Static electricity and surge can lead to changes in product characteristics, such as forward voltage reduction, which can be serious and even damage the product. So for the whole process (production, testing, packaging, etc.) and LED direct contact staff should do a good job to prevent and eliminate electrostatic measures. All related equipment and machinery should be properly grounded. The grounding ac resistance is less than 1.0 ohm, the table mat with surface resistance of 10^6 - 10^9 ohm is needed on the work table. Ion fans must also be installed in electrostatic environments and equipment. During the operation, the operator should use anti-static bracelet, anti-static mat, anti-static overalls, working shoes, gloves, anti-static capacity.

电烙铁焊接 An electric soldering iron

建议使用防静电电烙铁, 尖端处温度不超过 350°C , 每次焊接时少于 3 秒。电烙铁的功率宜低于 60W 。每焊完一次之后间隔 2 秒以上, 分别焊好两个电极引脚。焊接时不可对透镜用力施压。LED 如有问题一般都是从焊接时开始出现。故必须按要求小心作业。

It is recommended to use anti-static electric soldering iron, the temperature at the tip does not exceed 350°C , less than 3 seconds for each soldering. The power of the soldering iron should be less than 60W . Weld two electrode pins more than 2 seconds after each welding. Do not force the lens during welding. Problems with leds usually begin when they are soldered. So you must work carefully as required.

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